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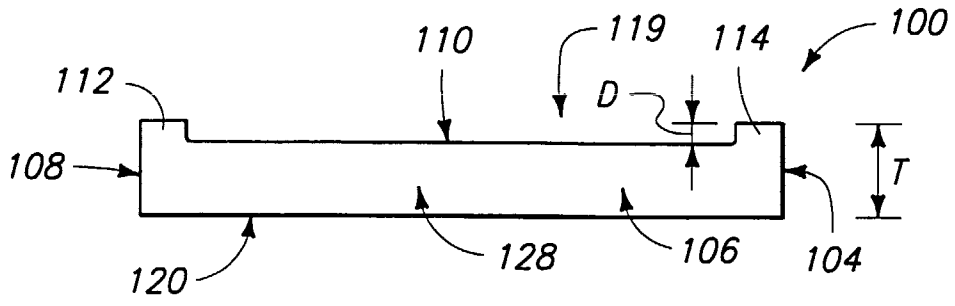
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(54) Title: LID AND HEAT SPREADER DESIGN FOR A SEMICONDUCTOR PACKAGE




(57) Abstract: The invention encompasses microelectronic package lids, heat spreaders, and semiconductor packages comprising microelectronic lids or heat spreaders. In particular aspects of the present invention, a microelectronic lid comprises a material having a rectangular peripheral shape that defines 4 peripheral sides. Further, the lid has projecting peripheral rails (112) along less than all of the peripheral edge. For instance, the lid can have projecting peripheral rails along only 2 of the sides. Alternatively, such microelectronic lid can be described as comprising a generally rectangular shape defining four peripheral edges, with two of the edges having a greater thickness than the other two edges.

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